

Amendments to the Specification:

Please replace the paragraph beginning at page 1, line 4, with the following rewritten paragraph:

- 5 — The present invention relates to an integrated circuit package having a
resistant layer for stopping flowed glue~~central leads~~, and more particularly to an
integrated circuit package which may be conveniently manufactured with reduced
manufacturing costs. —

10 Please replace the two paragraphs beginning at page 1, line 8, with the
following rewritten paragraphs:

- Referring to FIG. 1, a conventional integrated circuit package having
central leads includes a substrate 10, a glue layer 12, an integrated circuit 14, a
plurality of wires 16, and a compound layer 18. The substrate 10 has an upper
surface 20, a lower surface 22 and a long slot 24 penetrating from the upper
15 surface 20 to the lower surface 22, wherein the lower surface 22 of the substrate
10 is formed with wiring regions 26 arranged at the two sides of the long slot 24,
and the wiring region 26 is formed with ~~connected~~ connection points 28. The glue
layer 12 is coated on the upper surface 20 of the substrate 10, and is located at the
periphery of the long slot 24. The integrated circuit 14 has a first surface 30 and a
20 second surface 32, wherein the central portion of the first surface 30 of the
integrated circuit 14 is formed with bonding pads 34, while the first surface 30 of
the substrate 10 is adhered to the glue layer 12, so ~~that as to~~ the bonding pads 34
of the substrate 10 are exposed from the long slot 24 ~~slot 24~~. The wires are
arranged within the long slot 24 of the substrate 10, and ~~are electrically connected~~
25 the bonding pads 34 of the integrated circuit 14 to the ~~connected~~ connection
points 28 of the substrate 10. The compound layer 18 is filled within the long slot
24 ~~for protecting to protect~~ the wires.

- However, the above-mentioned integrated circuit ~~image package~~ has the
following drawbacks. When the glue layer 12 is coated on the upper surface 20 of
30 the substrate 10, the flowed glue of the glue layer 12 ~~is covered on~~ covers the
wiring region 26 through the long slot 24 of the substrate 10, so that the ~~connected~~

connection points 28, which are arranged at the wiring region 26, are covered by the flowed glue. —

Please replace the four paragraphs beginning at page 2, line 9, with the
5 following rewritten paragraphs:

— An object of the present invention is to provide an integrated circuit package, which is capable of preventing the flowed glue of the glue layer from
~~covered~~covering the wiring region, so that the wire bonding is easy.

Another object of the present invention is to provide an integrated circuit
10 package ~~having central leads~~, which may be conveniently manufactured with reduced manufacturing costs.

To achieve the above-mentioned objects, the present invention provides an integrated circuit package ~~having central leads~~ ~~includes~~ including a substrate, a glue layer, an integrated circuit, a plurality of wires, and a first compound layer.
15 The substrate has an upper surface, a lower surface, and ~~—~~ ~~and~~ a long slot penetrating from the upper surface to the lower surface, wherein the lower surface is ~~forming~~ formed with wiring regions arranged at the two sides of the long slot, and the wiring regions are ~~forming~~ formed with a plurality of ~~connected~~ connection points. The resistant layer is coated on and in contact with the lower
20 surface of the substrate, and is located between the long slot and the wiring region. The glue layer is coated on the upper surface of the substrate and arranged at the periphery of the long slot. The integrated circuit has a first surface ~~forming~~ formed with a plurality of bonding pads and a second surface, wherein the first surface is adhered to the glue layer, ~~then~~ and the bonding pads are exposed from
25 the long slot of the substrate. The wires, each of which is arranged within the long slot of the substrate, ~~and is electrically connected~~ connect the bonding pads of the integrated circuit to the ~~connected~~ connection points of the substrate, respectively. The first compound layer is filled within the long slot of the substrate ~~for to~~ protecting the ~~each~~ wires.

30 Utilizing the resistant layer to prevent the flowed glue from covering the
~~covered~~ ~~the~~ ~~connected~~ connection points may easily achieve the objects and

functions of the invention. —

Please replace the two paragraphs beginning at page 3, line 14, with the following rewritten paragraphs:

5 -- FIG. 2 is a cross-sectional view showing an integrated circuit package having central leads of the present invention.

FIG. 3 is a top-view of showing the substrate of the present invention. --

10 Please replace the eight paragraphs beginning at page 3, line 18, with the following rewritten paragraphs:

-- Referring to FIG. 2, an integrated circuit package having central leads of the present invention includes a substrate₄₀, a resistant layer₄₂, a glue layer₄₄, an integrated circuit₄₆, a plurality of wires₄₇, a first compound layer₄₈, and a second compound layer₅₀.

15 The substrate₄₀ has an upper surface₅₂, a lower surface₅₄, and a long slot 56 penetrating from the upper surface₅₂ to the lower surface₅₄. The lower surface₅₄ of the substrate₄₀ is formed with wiring regions₅₈ arranged at the two sides of the long slot₅₆, and the wiring regions₅₈ are formed with a plurality of connected connection points₆₀, each of which is are formed with a ball grid array. Please referring to FIG. 3, the length of the wiring region 60-58 is shorter than that of the long slot₅₆ of the substrate₄₀. Therefore, while the long slot₅₆ of the substrate is drilled, the periphery of the long slot₅₆ may be cracked, so that and the flowed glue of the glue layer₄₄ can not flow to the wiring regions₅₈ via the cracked according to the resistant layer 42. The resistant layer 42 separates the
25 long slot 56 from the wiring region 58. A length of the resistant layer 42 is substantially equal to the length of the wiring region 58.

The resistant layer₄₂ is coated on the lower surface₅₄ of the substrate₄₀, and is located between the long slot₅₆ and the wiring region₅₈. In preferred the embodiment, the resistant layer₄₂ is made of green.

30 The glue layer₄₄ is coated on the upper surface₅₂ of the substrate₄₀, and is located at the periphery of the long slot₅₆.

The integrated circuit_46 has a first surface_62 on which a plurality of bonding pads_66 are formed, and a second surface_64. The first surface_62 is adhered to the glue layer_44, ~~thus, and~~ the bonding pads_66 are exposed from the long slot_56 of the substrate_40.

- 5 The plurality of wires_47, each of which is arranged within the long slot_56 of the substrate_40, ~~and is electrically connected the bonding pads_66 of the integrated circuit_46 to the connected connection points_60 of the substrate_40.~~

The first compound layer_48 is filled within the long slot_56 of the substrate 40 ~~for protecting to protect the each wire_47, respectively.~~

- 10 The second compound layer_50 is covered on the upper surface_52 of the substrate_40 to ~~prevent protect~~ the integrated circuit_46. --

Please replace the two paragraphs beginning at page 5, line 6, with the following rewritten paragraphs:

- 15 -- 1. Since if the flowed glue of the glue layer_44 ~~is flowed flows~~ to the lower surface_54 of the substrate_40 through the long slot_56, the resistant layer 42 prevents the flowed glue ~~can be prevented by the resistant layer_42 to from flowing~~ to the wiring regions_58, so that the ~~connected connection points_60 may not cannot be~~ covered by the flowed glue.

- 20 2. ~~Since the length of each of the wiring regions_58 are is shorter than that of the long slot_56, so that, while drilled the long slot_56, So, if the substrate_40 is cracked while the long slot_56 is being drilled, which is can be not coupled to the wiring regions_58, thus the connected the connection points_60 can be not covered by the flowed flue of the glue layer_44. --~~

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